

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) ~~An exposure apparatus including a main body of the exposure apparatus which exposes a pattern onto a substrate, the exposure apparatus being accommodated in a chamber, comprising~~ with a light beam from a mask in a main body, comprising:

~~a plurality of air conditioning chambers which are formed by dividing said chamber~~ a chamber in which the main body is provided and that has a plurality of air-conditioning chambers including a column chamber which houses a stage on which the substrate is placed, an exposure chamber which houses the main body, a mask transfer system housing chamber which houses a mask transfer system to transfer the mask, and a substrate transfer system housing chamber which houses a substrate transfer system to transfer the substrate, wherein a relational expression $P_C \geq P_{WL} \geq P_B \geq P_{RL}$ is satisfied, where P_C is a pressure of the column chamber, P_B is a pressure of the exposure chamber, P_{RL} is a pressure of the mask transfer system housing chamber, and P_{WL} is a pressure of the substrate transfer system housing chamber; and

~~a pressure detection device which detects pressure information relating to said~~ a pressure detection device which detects pressure information relating to ~~with respect to the plurality of air-conditioning chambers.~~

2. (Currently Amended) An exposure apparatus according to claim 1, further comprising:

a pressure controlling device which adjusts pressure in each of said air-conditioning chambers, wherein

said pressure controlling device adjusts the pressure based on ~~detection results from said pressure detection device so that a predetermined pressure difference is generated~~

~~among each of said plurality of air conditioning chambers~~ the pressure information detected
so that the relational expression is satisfied.

3. (Original) An exposure apparatus according to claim 2, wherein:

said pressure controlling device performs said adjustment by controlling at least one of a gas supplying amount and a gas exhaust amount with respect to each of said air-conditioning chambers.

4. (Original) An exposure apparatus according to claim 3, further comprising:

a supply passage and an exhaust passage connected to each of said air-conditioning chambers, wherein

said pressure controlling device includes a passage opening rate adjusting unit which is provided with at least one of the supply passage and the exhaust passage, and adjusts a gas flow rate by adjusting an opening rate of the passage.

5. (Currently Amended) An exposure apparatus according to claim 1, ~~further comprising; wherein~~

~~————— an exposure stage on which said substrate is mounted and subjected to an exposure process, wherein~~

~~————— one of said plurality of air conditioning chambers is a column chamber which accommodates said exposure stage; and~~

~~————— said pressure controlling device adjusts a the pressure of said column chamber so as to be is higher than said plurality of air conditioning chambers other than said column chamber the pressure of the substrate transfer system housing chamber.~~

6. (Currently Amended) An exposure apparatus according to ~~claim 5, wherein~~ ~~said plurality of air conditioning chambers other than said column chamber includes:~~

~~————— an exposure chamber which accommodates said main body of the exposure apparatus;~~

~~_____ a mask transfer system accommodating chamber in which a mask transfer system is accommodated, said mask transfer system transferring a mask on which said pattern is formed into said main body of the exposure apparatus, and transferring the mask from said main body of the exposure apparatus; and~~

~~_____ a substrate transfer system accommodating chamber in which a substrate transfer system is accommodated, said substrate transfer system transferring said substrate into said main body of the exposure apparatus, and transferring said substrate from said main body of the exposure apparatus; wherein~~

~~_____ said pressure controlling device performs said adjustment so as to satisfy:~~

$$\text{_____ } P_C \geq P_{WL} \geq P_B \geq P_{RL}$$

~~where P_C is a pressure of said column chamber, P_B is a pressure of said exposure chamber, P_{RL} is a pressure of said mask transfer system accommodating chamber, and P_{WL} is a pressure of said substrate transfer system accommodating chamber claim 1, wherein $P_{WL} \geq P_{CD}$ is satisfied where P_{CD} is a pressure of a substrate processing device which is connected to the exposure apparatus.~~

7. (Currently Amended) An exposure apparatus according to ~~claim 6~~, claim 1, wherein

$P_{RL} \geq P_{CR}$ is satisfied where P_{CR} is a pressure of a predetermined environment of the exposure apparatus.

8. (Currently Amended) An exposure apparatus ~~including a main body of the exposure apparatus which exposes a pattern onto a substrate, the exposure apparatus being accommodated in a chamber, comprising with a light beam from a mask in a main body,~~ comprising:

~~_____ a plurality of air conditioning chambers which are formed by dividing said chamber; and~~

~~_____ a pressure controlling device which adjusts pressure in each of said air conditioning chambers, wherein~~

~~_____ said plurality of air conditioning chambers include:~~

~~_____ a column chamber which accommodates an exposure stage on which said substrate is mounted and subjected to an exposure process;~~

~~_____ an exposure chamber which accommodates said main body of the exposure apparatus;~~

~~_____ a mask transfer system accommodating chamber in which a mask transfer system is accommodated, said mask transfer system transferring a mask on which said pattern is formed into said main body of the exposure apparatus, and transferring the mask from said main body of the exposure apparatus; and~~

~~_____ a substrate transfer system accommodating chamber in which a substrate transfer system is accommodated, said substrate transfer system transferring said substrate into said main body of the exposure apparatus, and transferring said substrate from said main body of the exposure apparatus; wherein~~

_____ a chamber in which the main body is provided and that has a plurality of air conditioning chambers including a column chamber which accommodates a stage on which the substrate is placed, an exposure chamber which accommodates the main body, a mask transfer system accommodating chamber which accommodates a mask transfer system to transfer the mask, and a substrate transfer system accommodating chamber which accommodates a substrate transfer system to transfer the substrate; and

_____ said a pressure controlling device which adjusts pressure in at least one of the air-conditioning chambers performs said adjustment so as to satisfy:

$$P_C \geq P_{WL} \geq P_B \geq P_{RL}$$

where P_C is a pressure of said column chamber, P_B is a pressure of said exposure chamber, P_{RL} is a pressure of said mask transfer system accommodating chamber, and P_{WL} is a pressure of said substrate transfer system accommodating chamber.

9. (Original) An exposure apparatus according to claim 8, wherein

$P_{RL} \geq P_{CR}$ is satisfied where P_{CR} is a pressure of a predetermined environment of the exposure apparatus.

10. (Original) An exposure apparatus according to claim 9, wherein

$P_{WL} \geq P_{CD}$ is satisfied where P_{CD} is a pressure of a substrate processing device which is in-line connected to the exposure apparatus.

11. (Original) An exposure apparatus which transfers a pattern of a first object onto a second object, comprising:

a first chamber in which at least said first object of a main body of the exposure apparatus which exposes said second object using an illumination beam via said first object is disposed;

a second chamber in which at least said second object of said main body of the exposure apparatus is disposed;

a third chamber in which a first transfer system is disposed which transfers said first object to/from said first chamber;

a fourth chamber in which a second transfer system is disposed which transfers said second object to/from said second chamber; and

a gas supply device which supplies a gas to each of said first chamber, second chamber, third chamber, and fourth chamber, at least a temperature of said gas being controlled; wherein

pressure of each of said chambers is set so as to satisfy:

$$P_C \geq P_{WL} \geq P_B \geq P_{RL}$$

where P_B is a pressure of said first chamber, P_C is a pressure of said second chamber, P_{RL} is a pressure of said third chamber, and P_{WL} is a pressure of said fourth chamber.

12. (Original) An exposure apparatus according to claim 11, wherein the pressure of each of said chambers is set to be about the same or higher than a pressure P_{CR} of a predetermined environment of the exposure apparatus.

13. (Original) An exposure apparatus according to claim 12, wherein the pressure of each of said chambers is set to be higher than the pressure P_{CR} of the predetermined environment, and the pressure P_{RL} of said third chamber is set so that a difference in pressure with respect to the predetermined environment becomes about 0.5 [Pa] or greater.

14. (Original) An exposure apparatus according to claim 13, wherein the pressure P_C of said second chamber is set so that a difference in pressure with respect to the predetermined environment becomes about 1.5 [Pa] or smaller.

15. (Previously Presented) An exposure apparatus according to claim 11, wherein the pressure P_{WL} of said fourth chamber is set to be about the same or higher than a pressure P_{CD} of a substrate processing device which is in-line connected to the exposure apparatus.

16. (Original) An exposure apparatus according to claim 15, wherein the pressure P_{WL} of said fourth chamber is set to be higher than the pressure P_{CD} of said substrate processing device and lower than the pressure P_C of said second chamber.

17. (Original) An exposure apparatus according to claim 16, wherein

the pressure P_{WL} of said fourth chamber is set to be higher than the pressures P_B and P_{RL} of said first and third chambers, respectively.

18. (Original) An exposure apparatus according to claim 15, further comprising:
a pressure detection device which detects pressure information relating to at least one of said first, second, third, and fourth chambers.

19. (Previously Presented) An exposure apparatus according to claim 11, wherein
the pressure P_{WL} of said fourth chamber is set to be higher than the pressures P_B and P_{RL} of said first and third chambers, respectively.

20. (Original) An exposure apparatus according to claim 19, wherein
the pressure P_C of said second chamber is set to be higher than the pressure P_{WL} of said fourth chamber.

21. (Original) An exposure apparatus according to claim 19, further comprising:
a pressure detection device which detects pressure information relating to at least one of said first, second, third, and fourth chambers.

22. (Previously Presented) A device manufacturing method, comprising the step of transferring a pattern onto a photosensitive object using an exposure apparatus according to claim 1.